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One-stop services for PICs: from design to testing

As data center transceivers, LIDAR, quantum systems and biosensors are commencing to scale up, several challenges are emerging now in their design and testing. Building reliable component models on top of mature foundry processes is key, and that requires for extensive functional characterization and process validation, both at wafer and die level. Another key aspect when moving forward in the product development phases is the need for reliability testing, which is proving to be more difficult in PICs than in discrete optical components.